SDAS217A - DECEMBER 1982 - REVISED DECEMBER 1994

- 8-Bit Parallel-Out Storage Register Performs Serial-to-Parallel Conversion With Storage
- Asynchronous Parallel Clear
- Active-High Decoder
- Enable/Disable Input Simplifies Expansion
- Expandable for n-Bit Applications
- Four Distinct Functional Modes
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

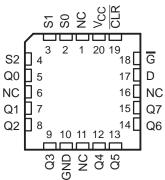
description

These 8-bit addressable latches are designed for general-purpose storage applications in digital systems. Specific uses include working registers, serial-holding registers, and active-high decoders or demultiplexers. They are multifunctional devices capable of storing single-line data in eight addressable latches and being a 1-of-8 decoder or demultiplexer with active-high outputs.

Four distinct modes of operation are selectable by controlling the clear (\overline{CLR}) and enable (\overline{G}) inputs as shown in the function table. In the addressable-latch mode, data at the data-in terminal is written into the addressed latch. The

SN54ALS259 J PACKAGE SN74ALS259 D OR N PACKAGE (TOP VIEW)									
S0 [S1 [Q0 [Q1 [Q2 [Q3 [GND [3 4 5 6	U	16 15 14 13 12 11 10 9] V _{CC}] CLR] G] D] Q7] Q6] Q5] Q4					

SN54ALS259 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

addressed latch follows the data input with all unaddressed latches remaining in their previous states. In the memory mode, all latches remain in their previous states and are unaffected by the data or address inputs. To eliminate the possibility of entering erroneous data in the latches, \overline{G} should be held high (inactive) while the address lines are changing. In the 1-of-8 decoding or demultiplexing mode, the addressed output follows the level of the D input with all other outputs low. In the clear mode, all outputs are low and unaffected by the address and data inputs.

The SN54ALS259 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ALS259 is characterized for operation from 0°C to 70°C.

	FUNCTION											
INPU	INPUTS OUTPUT OF EACH ADDRESSED OTHER FUNCTION											
CLR	G	ADDRESSED LATCH	OTHER OUTPUT	FUNCTION								
Н	L	D	Q _{iO}	Addressable latch								
н	Н	QiO	Q _{iO}	Memory								
L	L	D	L	8-line demultiplexer								
L	Н	L	L	Clear								

Function Tables

D = the level at the data input.

 Q_{iO} = the level of Q_i (i = Q, 1, . . . 7 as appropriate) before the indicated steady-state input conditions were established.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



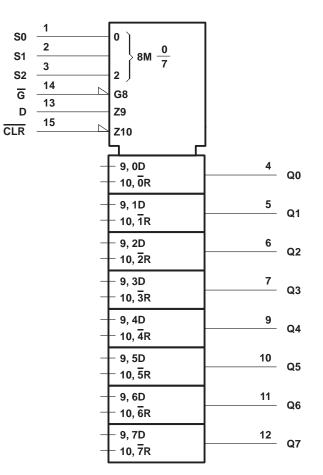
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Function Tables (Continued)

	LATC	H SELEC	CTION
SEL	ECT INP	UTS	LATCH
S2	S 1	S0	ADDRESSED
L	L	L	0
L	L	Н	1
L	Н	L	2
L	Н	Н	3
Н	L	L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	Н	7

logic symbol[†]

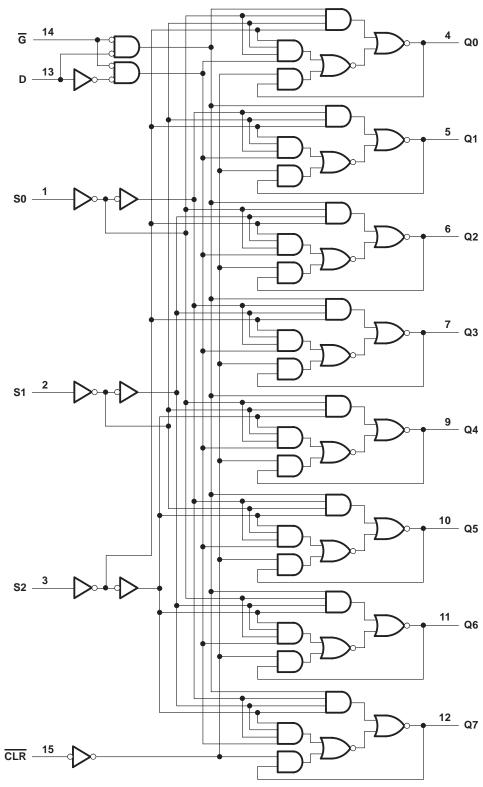


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.



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logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Operating free-air temperature range, TA: SN54AI	LS259
	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			SN	54ALS2	59	SN	74ALS2	59	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIН	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	V
IOH	High-level output current				-0.4			-0.4	mA
IOL	Low-level output current				4			8	mA
	Delas desettes	G low	20			15			
tw	Pulse duration	CLR low	10			10			ns
	O atom time a	Data before G↑	20			15			
t _{su}	Setup time	Address before \overline{G}	20			15			ns
		Data after G↑	0			0			
th	Hold time	Address after \overline{G}	0			0			ns
Тд	Operating free-air temperature		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS				SN74ALS259			
PARAMETER	TEST C	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	lı = – 18 mA			-1.5			-1.5	V
VOH	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		V
		$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V _{OL}	$V_{CC} = 4.5 V$	I _{OL} = 8 mA					0.35	0.5	V
lj	$V_{CC} = 5.5 V,$	$V_{I} = 7 V$			0.1			0.1	mA
Ιн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
۱ _О §	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V			14	22		14	22	mA

[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.



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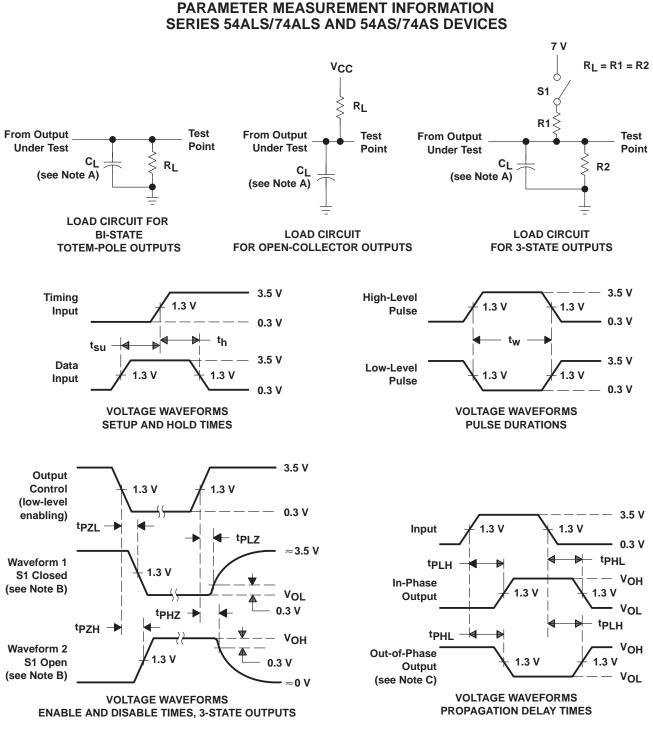
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL TA	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [†] SN54ALS259 SN74ALS259					
			MIN	MAX	MIN	MAX			
tPHL	CLR	Any Q	2	15	2	12	ns		
^t PLH			4	22	4	19			
^t PHL	Data	Any Q	2	15	2	12	ns		
^t PLH	Ashinasa	A O	4	26	4	22			
^t PHL	Address	Any Q	2	15	2	12	ns		
^t PLH	Execute	Any Q	4	22	4	20	ns		
^t PHL	Execute	Any Q	2	16	2	13	115		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- . When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_f = t_f = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
5962-8874101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8874101EA SNJ54ALS259J	Samples
SN54ALS259J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	SN54ALS259J	Samples
SN74ALS259D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS259	Samples
SN74ALS259DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS259	Samples
SN74ALS259DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS259	Samples
SN74ALS259N	ACTIVE	PDIP	Ν	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS259N	Samples
SNJ54ALS259J	ACTIVE	CDIP	J	16	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-8874101EA SNJ54ALS259J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

6-Feb-2020

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS259, SN74ALS259 :

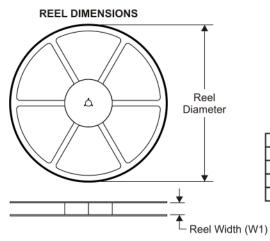
- Catalog: SN74ALS259
- Military: SN54ALS259

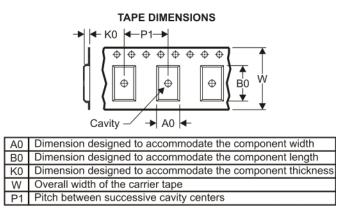
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

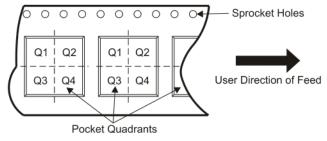
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



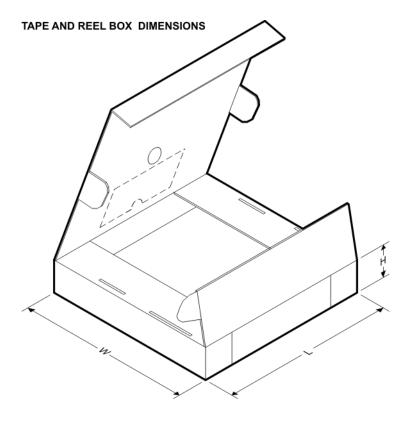
*All dimensions are nominal	
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Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS259DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

19-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS259DR	SOIC	D	16	2500	333.2	345.9	28.6

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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